



Bill of Materials

TI DESIGNS

TIDM-SUB1GHZ-MESH-NETWORK

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	X1	26MHz	Crystal Oscillator				XIAL4P-SMT3*2X5	
2	1	X2	32768Hz	Crystal Oscillator				XIAL-2*5V - noSMT	
3	1	C1	1pF	Capacitor				C/0402	
4	2	C2, C20	1uF	Capacitor				C/0402	
5	3	C3, C4, C14	33pF	Capacitor				C/0402	
6	5	C5, C15, C16, C19, C21	100nF	Capacitor				C/0402	
7	2	C6, C7	100pF	Capacitor				C/0402	
8	2	C8, C9	1.5pF	Capacitor				C/0402	
9	1	C10	3.3pF	Capacitor				C/0402	
10	1	C12	12pF	Capacitor				C/0402	
11	1	C13	47pF	Capacitor				C/0402	
12	2	C17, C18	22pF	Capacitor				C/0402	
13	1	D1		DIP6 Connector				Con6p_1mm	
14	1	J1		SMA connector				SMB_V-RJ45	
15	1	JTAG		DIP8 Connector				CN8P-2.0 - NoBoard	
16	4	L1, L2, L5, L6	12nH	Inductor				0402-A	
17	2	L3, L4	18nH	Inductor				0402-A	
18	1	L7	3.3nH	Inductor				0402-A	
19	1	R1	56k ohm	Resistor				R/0402	
20	1	R2	47k ohm	Resistor				R/0402	
21	1	R3	10 ohm	Resistor				R/0402	
22	1	U1		CC1101				IC-QFN20-RTJ4X4	
23	1	U2		MSP430G2533				IC-SSOP28(DBQ)	

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